

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KENICHI TAMURA	08/11/2014
YOSHINORI SUNAGA	08/11/2014
RECEIVING PARTY DATA	
Name:	HITACHI METALS, LTD.
Street Address:	2-1, SHIBAURA 1-CHOME
City:	MINATO-KU, TOKYO
State/Country:	JAPAN
Postal Code:	105-8614
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14469034
CORRESPONDENCE DATA	
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Address Line 4:	WASHINGTON, D.C. 20004
ATTORNEY DOCKET NUMBER:	109853.66969US
NAME OF SUBMITTER:	MICHAEL H. JACOBS
SIGNATURE:	/Michael H. Jacobs/
DATE SIGNED:	09/17/2014
Total Attachments: 1	
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ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi Metals, Ltd.,
a corporation organized under the laws of Japan,
located at 2-1, Shibaura 1-chome Minato-ku, Tokyo, 105-8614, Japan,
receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Metals, Ltd.,
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

JIG FOR CAN-PACKAGE SEMICONDUCTOR LASER

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi Metals, Ltd.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Metals, Ltd.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) <u>Kenichi Tamura</u> (Kenichi TAMURA)	<u>8 / 11 / 2014</u>
2) <u>Y. Sunaga</u> (Yoshinori SUNAGA)	<u>8 / 11 / 2014</u>
3) _____	_____
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____

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